

LUXBEAM® LLS02

Advanced packaging at 2 μm

A 405 / 375 nm laser photohead for the finest interconnect outside the sub-micron node — CPO and glass-core RDL, fan-out packaging, MEMS and microfluidics, on wafers and panels up to 510 × 515 mm.

Full specification

IMAGING & LAYOUT	
Resolution	2 μm
Light source	405 / 375 nm laser
Throughput — Ø300 mm wafer	60 wph
Throughput — 515 × 510 mm panel	20 pph
Typical applications	CPO RDL, glass-core / interposer RDL, FOWLP, MEMS, microfluidics
Substrate / panel	Wafers, 310×310, 510×515
Segment	Advanced packaging

Figures are for discussion and to be confirmed per application. Throughput depends on resist and energy density — send us both and a field application engineer will verify them for your process.